

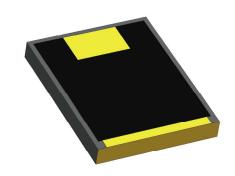
TERMINATION

CVD DIAMOND CHIP 125 WATTS

Rev A1.0

General Description

CVD Diamond Chip Terminations offer a unique combination of extreme high power ratings in very small packages. These terminationsmay be used in applications up to 30 GHz and are ideal for applications with requirements for high power capability, broad frequency response, small footprint and light weight. The terminations are manufactured using all thin film construction and have a gold finish that it both wire bondable and solderable. This total thin film construction also makes them ideal for peak power applications. High reliability tested versions based on MIL-PRF-55342 are also available. Select from tape and eel, bulk, or waffle packaging. These products are also lead free, RoHS compliant and S-level approved.



Features:

- Small Size-Light Weight
- Highest Thermal Perfomance Possble
- Excellent Peak Power Capability
- Rugged Passivated TaN Film
- Moisture Tesistant
- Pure Gold Input Pads
- Wire Bondable or Solderable
- High Power

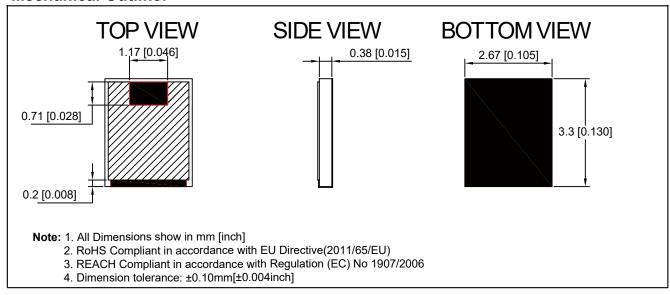
Specifications

Operating Temperature: -55 °C To +150 °C Storage Temperature: -55 °C To +150 °C Temperature Coefficient: ± 200 PPM/°C Max

Applications:

- Broadcast
- Higher Power Filters
- High Power Amplifiers
- Instrumentation
- Isolators
- Military
- Satellite Communications
- Phased Array Radar

Mechanical Outline:





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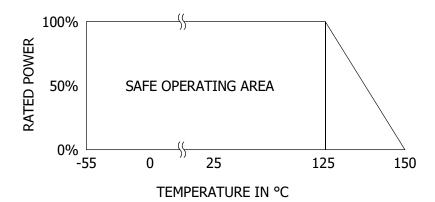
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Mechanical

Substrate Material: CVD Diamond
Terminal Material: Gold over Nickel
Ground Plane Material: Gold over Platinum

Resistive Element: Thin Film

Metric Dimensions: Provided for reference only



Typical Performance

Return Loss



Frequency (GHz)

Yantel Corporation